Overview

HP ZBook Firefly 16" G9 Mobile Workstation PC



- 1. Ambient Light Sensor (Optional)
- 2. Internal Microphones (2)
- 3. Webcam LED (Optional)
- 4. Webcam
- 5. Camera Shutter
- 6. IR Camera (Optional)
- 7. IR Camera LEDs (Optional)

Right

- 8. Clickpad
- 9. Power Button Key
- 10. Audio Combo Jack
- 11. SuperSpeed USB Type-A 5Gbps signaling rate
- 12. Nano Security Lock Slot (Lock sold separately)
- 13. SIM Card Slot (Optional)
- 14. Touch Fingerprint Sensor (Select models)

Overview



Left

- 1. HDMI 2.0b Port (Cable not included)
- 2. SuperSpeed USB Type-A 5Gbps signaling rate (Charging)
- 3. 2 Thunderbolt[™] 4 with USB4 Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)1
- 4. LED Indicator
- 5. Smartcard Reader (Optional)



Overview



Bottom

1. Fan Venting



Overview

At A Glance

- New premium ultraslim design with precision-crafted all-metal chassis for a premium look and feel
- 12th Generation Intel® Core™ i5, i7 U-series and i5, i7 P-series Processors up to fourteen-core
- Preinstalled with Windows 11 versions or FreeDOS
- New 16:10 ratio screen reduces the need to scroll by showing more vertical content than 16:9
- New 5MP camera² with HP Auto Frame¹ allows you around a little without losing viewers' attention during video calls
- New DDR5 memory and PCI Gen4 SSDs provide fast access to your work.
- · Choice of displays:
 - 40.6 cm (16") diagonal WUXGA IPS Anti-Glare LED-backlit non-touch, 250 nits, 45% NTSC
 - 40.6 cm (16") diagonal WUXGA IPS Anti-Glare On-Cell LED-backlit touch, 250 nits, 45% NTSC
 - 40.6 cm (16") diagonal WUXGA IPS Anti-Glare LED-backlit non-touch, 400 nits, 100% sRGB
 - 40.6 cm (16") diagonal WUXGA IPS Anti-Glare LED-backlit non-touch, 1000 nits, 100% sRGB with HP Sure View Reflect
- Choose from 51Whr or 76Whr battery options
- HP Wolf Security for Business creates a hardware-enforced, always-on, resilient defense.
- Larger Clickpad surface for easier, more intuitive input
- Connectivity with optional Intel® 5000 5G/WWAN available world-wide, and Thunderbolt™ Docking (Dock sold separately)
- Passes 19 MIL-STD 810H tests⁶
- Supports fast charging (50% in 30 minutes) with no impact on battery recharge cycles³
- Designed to support all HP docking options including the HP Universal Dock G5

²Optional feature that must be configured at the time of purchase.

³HP Presence requires mvHP application and Windows OS.

⁴Requires Windows OS.

⁵HP Wolf Security for Business requires Windows 10 and higher, includes various HP security features and is available on HP Pro, Elite, Workstation, and RPOS products. See product details for included security features and OS requirements.

⁶MIL-STD 810GH is not intended to demonstrate fitness of U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

⁷SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



¹Requires the mvHP application and Windows OS.

Features

OPERATING SYSTEM

Preinstalled OS

Windows 11 Pro - HP recommends Windows 11 Pro for business 2

Windows 11 Pro Education 2

Windows 11 Home - HP recommends Windows 11 Pro 2

Windows 11 Home Single Language - HP recommends Windows 11 Pro ²

Windows 11 Pro (Windows 11 Enterprise available with a Volume Licensing Agreement) 2

Windows 10 Pro (available through downgrade rights from Windows 11 Pro)^{1,2,3}

FreeDOS

¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

PROCESSOR

12th Generation Intel® Core™ i7-1280P (1.3 GHz E-core base frequency, 1.8 GHz P-core base frequency, up to 3.6 GHz E-core Max Turbo Frequency, up to 4.8 GHz P-core Max Turbo frequency with Intel® Turbo Boost Technology, 24 MB L3 cache, 6 P-cores and 8 E-cores, 20 Threads) Supporting Intel® vPro® technology 1.2.3.4.5

12th Generation Intel® Core™ i7-1270P (1.6 GHz E-core base frequency, 2.2 GHz P-core base frequency, up to 3.5 GHz E-core Max Turbo Frequency, up to 4.8 GHz P-core Max Turbo frequency with Intel® Turbo Boost Technology, 18 MB L3 cache, 4 P-cores and 8 E-cores, 16 Threads) Supporting Intel® vPro® technology 1.2.3.4.5

12th Generation Intel® Core™ i7-1260P (1.5 GHz E-core base frequency, 2.1 GHz P-core base frequency, up to 3.3 GHz E-core Max Turbo Frequency, up to 4.4 GHz P-core Max Turbo frequency with Intel® Turbo Boost Technology, 18 MB L3 cache, 4 P-cores and 8 E-cores, 16 Threads) ^{1,2,3,4}

12th Generation Intel® Core™ i5-1250P (1.2 GHz E-core base frequency, 1.7 GHz P-core base frequency, up to 3.3 GHz E-core Max Turbo Frequency, up to 4.4 GHz P-core Max Turbo frequency with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 P-cores and 8 E-cores, 16 Threads) Supporting Intel® vPro® technology 1.2,3,4,5

12th Generation Intel® Core™ i5-1240P (1.2 GHz E-core base frequency, 1.7 GHz P-core base frequency, up to 3.3 GHz E-core Max Turbo Frequency, up to 4.4 GHz P-core Max Turbo frequency with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 P-cores and 8 E-cores, 16 Threads) ^{1,2,3,4}

12th Generation Intel® Core™ i7-1265U (1.3 GHz E-core base frequency, 1.8 GHz P-core base frequency, up to 3.6 GHz E-core Max Turbo Frequency, up to 4.8 GHz P-core Max Turbo frequency with Intel® Turbo Boost Technology, 12 MB L3 cache, 2 P-cores and 8 E-cores, 12 Threads) Supporting Intel® vPro® technology ^{1,2,3,4,5}



Features

12th Generation Intel® Core™ i7-1255U (1.2 GHz E-core base frequency, 1.7 GHz P-core base frequency, up to 3.5 GHz E-core Max Turbo Frequency, up to 4.7 GHz P-core Max Turbo frequency with Intel® Turbo Boost Technology, 12 MB L3 cache, 2 P-cores and 8 E-cores, 12 Threads) ^{1,2,3,4}

12th Generation Intel® Core™ i5-1245U (1.2 GHz E-core base frequency, 1.6 GHz P-core base frequency, up to 3.3 GHz E-core Max Turbo Frequency, up to 4.4 GHz P-core Max Turbo frequency with Intel® Turbo Boost Technology, 12 MB L3 cache, 2 P-cores and 8 E-cores, 12 Threads) Supporting Intel® vPro® technology 1,2,3,4,5

12th Generation Intel® Core™ i5-1235U (0.9 GHz E-core base frequency, 1.3 GHz P-core base frequency, up to 3.3 GHz E-core Max Turbo Frequency, up to 4.4 GHz P-core Max Turbo frequency with Intel® Turbo Boost Technology, 12 MB L3 cache, 2 P-cores and 8 E-cores, 12 Threads) ^{1,2,3,4}

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

³ Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

⁵ Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro



Features

CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel® Iris® Xe Graphics 1, 3, 4, 5, 6

Discrete

NVIDIA® T550 Laptop GPU (4 GB GDDR6 dedicated)2,4

Supports

Support HD decode, DX12, HDMI 2.0b, HDCP 2.3

- ² Both UMA & Discrete configurations support 4 independent displays when on the HP Thunderbolt Dock G2 (120W) (sold separately) Max. resolution = 2.5K @60Hz (DP1) & 2.5K @60Hz (DP2) & FHD (VGA) OR 4K @60Hz (one DP Port) & 4K @60Hz (Type-C output port using a Type C-to-DP adapter).
- ³ Support HD decode, DX12, HDMI 2.0b, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4096x2304 @ 60Hz
- ⁴ HDMI cable Sold Separately
- ⁵ Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.
- ⁶ Intel® Iris® Xe Graphics capabilities require system to be configured with Intel® Core™ i5 or i7 processors and dual channel memory. Intel® Iris® Xe Graphics with Intel® Core™ i5 or 7 processors and single channel memory will only function as UHD graphics.

DISPLAY

Non-touch

- 40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for 5MP camera (1920 x 1200)
- 40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for 5MP+IR camera (1920 x 1200)
- 40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for WWAN (1920 x 1200)
- 40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for 5MP camera for WWAN (1920 x 1200)
- 40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for 5MP+IR camera for WWAN (1920 x 1200)
- 40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP+PSR, 400 nits, 100% sRGB, Low Power, Ambient Light Sensor for 5MP Camera (1920 x 1200)
- 40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP+PSR, 400 nits, 100% sRGB, Low Power, Ambient Light Sensor+Ambient Color Sensor for 5MP+IR Camera (1920 x 1200)
- 40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP+PSR, 400 nits, 100% sRGB, Low Power, Ambient Light Sensor+Ambient Color Sensor for 5MP Camera for WWAN (1920 x 1200)
- 40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP1.3+PSR, 400 nits, 100% sRGB, Low Power, Ambient Light Sensor+Ambient Color Sensor for 5MP+IR Camera for WWAN (1920 x 1200)
- 40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP1.3+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor+Ambient Color Sensor for 5MP camera (1920 x 1200)
- 40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP1.3+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor+Ambient Color Sensor for 5MP+IR camera (1920 x 1200)
- 40.64 cm (16") diagonal WUXGA Bent, Low Blue Light, anti-glare UWVA eDP1.3+PSR, 1000 nits, 100% sRGB with HP Sure View Reflect integrated privacy screen, Ambient Light Sensor+Ambient Color Sensor for 5MP+IR camera for WWAN (1920 x 1200)



¹ UHD content required to view UHD images.

Features

Touch

- 40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for 5MP+IR camera Touch on Panel (1920 x 1200)
- 40.64 cm (16") diagonal WUXGA Bent, anti-glare UWVA, 250 nits, 45% NTSC for 5MP+IR camera for WWAN Touch on Panel (1920 x 1200)

DisplayPort™ 1.4

Support resolution up to 8K @60 Hz

Displays support

Supports up to 4 displays max through dock

¹HD content required to view HD images.

²Sold separately or as an optional feature.

³Resolutions are dependent upon monitor capability, and resolution and color depth settings.

⁴HP Sure View Reflect integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.

⁵Actual brightness will be lower with touchscreen or Sure View.



Features

DOCKING

Docking station model #1 **HP Thunderbolt Dock G2**

Total number of supported displays (incl.the notebook) display)

Max.resolutions supported

Dual 4K @30Hz or dual 4K UHD @ 60Hz is supported

Single 8K@ 30Hz (multiple tiles) for Thunderbolt hosts

Non-TBT hosts DP 1.4 in high res mode(1) 8K video single cable@30Hz

Dock Connectors

2xDP, 1xVGA, 1xTB, 1xUSB-C alt-mode

Technical limitations Thunderbolt Hosts:

4

Maximum of (4) displays with maximum resolution of 5K@ 30Hz running Thunderbolt host. Max resolution possible is dual 8K displays @ 60Hz running Thunderbolt host or running a

non-Thunderbolt host in High Resolution mode @30Hz

Non-Thunderbolt hosts:

The highest resolution for dual displays running a non-Thunderbolt host in multi-function

mode is

3

3

(1) 5K dual cable (using both DP ports) +(1) 4K on USB-C DP port

Non-Thunderbolt hosts support (3) displays with a max resolution of: (2) 5K single cable + (1) 4K UHD @ 60 Hz in high resolution mode. In multi-function mode the maximum resolution for (3) displays is (2) 5K single cable @ 30Hz + (1) 4K UHD @ 30Hz.

Docking station model #2

Total number of supported displays (incl.the notebook)

display)

Max.resolutions supported

Dock Connectors

Technical limitations

Dual 5K@ 30Hz + (1) 4K UHD (multi-function mode)

1xHDMI, 2xDP

HP USB-C Dock G5

Highest resolution with dual displays is two 8K@ 60Hz host in High Resolution mode.

Three maximum displays supported are two 5K@ 30 Hz on DP ports plus one 4K UHD@ 30

Hz on HDMI in multi-function mode

The highest resolution for a non-Thunderbolt host in Multi-function mode is a single 5K dual

cable (using both DP ports) + (1) 4K on HDMI port.

Docking station model #3

Total number of supported displays (incl.the notebook)

display)

HP USB-C/A Universal Dock G2

Triple 4K UHD@ 60Hz Max.resolutions supported

Dock Connectors 1xHDMI, 2xDP

Technical limitations The best resolution for dual or triple displays is 4K UHD@ 60Hz.

For use with the USB-A adapter that comes in the box the maximum number of displays

supported is (2) 4k x 60 Hz on the Type-A Gen 1 connection from the host



Features

STORAGE AND DRIVES*

PCle® NVMe™ M.2 2280 Storage

2 TB PCIe® Gen4x4 NVMe™ M.2 SSD TLC
1 TB PCIe® Gen4x4 NVMe™ M.2 SSD TLC
512 GB PCIe® Gen4x4 NVMe™ M.2 SSD TLC
512 GB PCIe® Gen4x4 NVMe™ SED TLC OPAL2
512 GB PCIe® NVMe™ Value M.2 SSD
256 GB PCIe® Gen4x4 NVMe™ M.2 SSD TLC
256 GB PCIe® Gen4x4 NVMe™ SED TLC OPAL2
256 GB PCIe® NVMe™ Value M.2 SSD

NOTE: Intel® Optane™ H10 memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

DRIVE CONTROLLERS

M.2 Storage Bay (PCIe NVMe) RAID:

Supports up to PCIe® Gen4 x4 lanes NVMe™ Solid State Drive Not supported

MEMORY

Maximum Memory

64GB DDR5-4800

Memory

64GB DDR5-4800 (2x32GB)

48GB DDR5-4800 (1x32GB+1x16GB)

32GB DDR5-4800 (2x16GB)

32GB DDR5-4800 (1x32GB)

16GB DDR5-4800 (2x8GB)

16GB DDR5-4800 (1x16GB)

8GB DDR5-4800 (1x8GB)

Memory Slots

2 SODIMM DDR5 SODIMMS, system runs at 4800 MT/s Supports Dual Channel Memory



Features

NETWORKING/COMMUNICATIONS

WLAN

Intel AX211 Wi-Fi6E+BT5.2 M.2 160MHz CNVi World-Wide WLAN vPro Intel AX211 Wi-Fi6E+BT5.2 M.2 160MHz CNVi World-Wide WLAN non-vPro

¹Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, and Windows 11 to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

WWAN1

Intel® 5000 5G Solution WWAN³
Intel® XMM 7560 R+ LTE-Advanced Pro WWAN(Cat 16)²

¹Mobile Broadband is an optional feature, Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE is not available on all products, in all regions.

²4G LTE module is optional, must be configured at the factory, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

³Intel 5G module is optional and must be configured at the factory. Module designed for 5G NR NSA (non-standalone) networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP. Module requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Data connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select platforms and select countries, where carrier supported.

Near Field Communication (NFC) module

No Near Field Communication (NFC) module NFC Mirage WNC XRAV-1

Miracast

Native Miracast Support

NOTE: Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen 2 Integrated stereo speakers Discrete Amplifiers Integrated dual array microphone

Speaker Power

2W/4ohm Per speaker

Camera^{1, 2}

5 MP camera

5 MP+IR camera



Features

Sensors

ALS (ambient light sensor) Magnetometer

Hall Sensor

Gyro

Accelerometer

HP Tamper Lock³



¹ HD content required to view HD images.

² Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.

³ HP Tamper Lock must be enabled by the customer or your administrator.

Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard*

HP Premium Keyboard, spill resistant, Backlit keyboard and DuraKeys HP Premium Keyboard, spill resistant, Non-Backlit keyboard and DuraKeys HP Premium Keyboard, spill resistant, Backlit keyboard and DuraKeys Privacy

Pointing Devices

Clickpad with multi-touch gesture support, taps enabled as default Microsoft Precision Touchpad Default Gestures Support

Function Keys

ESC: system information F1 - Display Switching F2 - Blank or Privacy F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Blank or Backlit Toggle

F10 - Insert

F11 - Airplane Mode

F12 - HP Command Center

Print Screen

Power Button (with LED)

delete

home

end

pg up

pg dn

Hidden Keys

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock

SOFTWARE AND SECURITY

Software

HP Quick Touch HP Quick Drop²¹

HP Easy Clean

HP PC Hardware Diagnostics Windows

HSA Fusion for Commercial

HSA Telemetry for Commercial

Touchpoint Customizer for Commercial

myHP

HP Smart Support²⁴

HP Connection Optimizer¹⁰

HP Mac Address Manager

HP Hotkey Support

HP Support Assistant¹

HP Notifications



^{*}Backlit keyboard is an optional feature.

Features

HP Privacy Settings HP Power Manager Buy Microsoft Office (Sold separately) HP audio Control³³

Manageability Features

HP Connect for Microsoft Endpoint Manager²⁶ HP Image Assistant Gen5 (download)

HP Manageability Integration Kit (download)12

HP Client Management Script Library (download)

HP Patch Assistant (download)27

HP Driver Packs (download)

HP Cloud Recovery 28

HP Client Catalog (download)

Security Management HP Wolf Security of Business ²⁹ includes:

HP Sure Click 30

HP Sure Sense¹⁹

HP Sure Run Gen5³¹

HP Sure Recover Gen514

HP Sure Start Gen7¹⁶

HP Tamper Lock

HP Sure Admin²³

HP Client Security Manager Gen7¹⁸

BIOS

HP BIOSphere Gen6⁶
HP Secure Erase¹⁷
Absolute Persistence Module⁷
HP DriveLock & Automatic DriveLock
BIOS Update via Network
HP Wake on WLAN
HP Fingerprint Sensor³²
Secured-Core PC Enable²⁰

TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

¹⁵ HP Sure Recover with Embedded Reimaging Gen3 is an optional feature which must be configured at purchase with a base unit that has the On System Recovery (OSR) module. See product specifications for availability You must back up important files, data, photos, videos, etc. before use to avoid loss of data. HP Sure Recover with Embedded Reimaging (Gen1) does not support platforms with Intel® Optane™.

¹⁶ HP Sure Start Gen7 is available on select HP PCs and requires Windows 10 and higher



¹ HP Support Assistant - Requires Windows and Internet Access.

⁶ HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations.

⁷ Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

¹⁰ HP Connection Optimizer requires Windows 10 and Windows 11.

¹² HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.

¹⁴ HP Sure Recover Gen5 with Embedded Reimaging is an optional feature which requires Windows 10 and higher must be configured at purchase. You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module

Features

- ¹⁷ HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- ¹⁸ HP Client Security Manager Gen7 requires Windows and is available on select HP Pro, Elite and ZBook PCs. See product specifications for details.
- 19 HP Sure Sense is available on select HP PCs with Windows 10 Pro, Windows 10 Enterprise, Windows 11 Pro, or Windows 11 Enterprise OS.
 20 Secured-core PC requires an Intel® vPro® or AMD Ryzen™ Pro processor. Requires 8 GB or more system memory. Secured-core PC functionality can be enabled from the factory.
- ²¹ Requires Internet access and Windows 10 PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.
- ²³ HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.
- ²⁴ HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.
- ²⁶ HP Connect for Microsoft Endpoint Manager is available from the Azure Market Place for HP Pro, Elite, Z and Point-of-Sale PCs managed with Microsoft Endpoint Manager. Subscription to Microsoft Endpoint Manager required and sold separately. Network connection required.
 ²⁷ HP Patch Assistant available on select HP PCs with the HP Manageability Kit that are managed through Microsoft System Center Configuration Manager. HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html.

- ²⁸ HP Cloud Recovery is available for Z by HP, HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630.
- ²⁹ HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features and OS requirement.
- ³⁰ HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
- ³¹ HP Sure Run Gen5 is available on select HP PCs and requires Windows 10 and higher.
- ³² HP Fingerprint Reader is an optional feature that requires Windows 10 IoT and must be configured at purchase.
- 33 Microphone Noise Reduction and Speaker Noise Reduction feature included under HP Audio Control



Features

POWER

Power Supply

HP Smart 65 W USB Type-C® adapter HP Slim 100 W USB Type-C® adapter

Battery

HP Long Life 3-cell, 51 Wh Polymer HP Long Life 6-cell, 76 Wh Polymer

Power Cord

3-wire plug - 1m 2-wire plug - 1m

Battery life

51Whr Battery:

Up to 12 hours (integrated Graphic configuration); Up to 10 hours (Discrete Graphics Configuration)

76Whr Battery:

Up to 18 hours (integrated Graphic configuration); Up to 14.5 hours (Discrete Graphics Configuration)

ENVIRONMENTAL

ENERGY STAR® certified

EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See www.epeat.net for registration status by country.

EPEAT® 2019 Gold

TCO 8.0 Certified

RCTA DO-160G

Medical EMC: IEC 60601-1-2:2014 EN60601-1-2: 2015

SEPA

GS Mark

Eyesafe Certification - Worldwide

Sustainable Impact Specifications

Recycled Aluminum and Magnesium, 75% PCR w/30% ITE plastics



¹ Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark18 battery benchmark https://bapco.com/products/mobilemark-2018/ for additional details.

² Supports HP Fast Charge Technology

³100W Power Adapter is only available with 76 Whr Battery.

⁴ Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

¹ Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

² External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

Features

WEIGHTS & DIMENSIONS

Dimensions (w x d x h) 14.12 x 9.88 x 0.76 in 35.87 x 25.1 x 1.92 cm

Weights*
Product Weight- 51Whr
Starting at 3.97 lb
Starting at 1.8 kg
Product Weight- 76Whr
Starting at 3.97 lb + 0.3lb = 4.27 lb
Starting at 1.8 kg + 138g = 1.938 kg

*Weight will vary by configuration. Does not include power adapter.

PORTS/SLOTS

- 2 Thunderbolt™ 4 with USB4 Type-C® 40Gbps signaling rate (USB Power Delivery, DisplayPort™ 1.4)
- 2 Super Speed USB Type-A 5Gbps signaling rate (1 charging)
- 1 HDMI 2.0
- 1 Headphone/microphone combo jack
- 1 Nano Security Lock Slot (Lock sold separately)
- 1 Smartcard reader (Optional)
- 1 nano SIM card slot (Optional)
- *SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.
- *HDMI cable sold separately.

SERVICE AND SUPPORT

1-year warranty and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.

¹Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.

SYSTEM UNIT

Stand-Alone Power Nominal Operating AC 20V Requirements (AC Power) Voltage

Average Operating System in idle mode Power(idle)

Integrated graphics Yes



Features

Shock

Random Vibration

Maximum Altitude

Planned Industry Standard

(unpressurized)

Certifications

N/A **Discrete Graphics** Max Operating Power UMA<65W

Temperature Operating 32° to 95° F (0° to 35° C)

> Non-operating 41° to 95° F (5° to 35° C) (writing optical)

Operating Relative Humidity 10% to 90%, non-condensing

> **Non-operating** 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Operating 40 G, 2 ms, half-sine **Non-operating** 200 G, 2 ms, half-sine

Operating 0.75 grms **Non-operating** 1.50 grms

> Operating -50 to 10,000 ft (-15.24 to 3,048 m) **Non-operating** -50 to 40,000 ft (-15.24 to 12,192 m)

Regulatory Model HSN-I45C-3

Number

UL Yes **CSA** Yes **FCC Compliance** Yes **ENERGY STAR®** Certified1 **EPEAT®** EPEAT 2.0 Gold²

ICES Yes Australia / NZ A-Tick Yes

Compliance

Yes Japan VCCI Compliance Yes KCC Yes **BSMI** Yes **CE Marking Compliance** Yes

MIL STD 810H Yes, 19 tests

BNCI or BELUS Yes CIT Yes **GOST** Yes Saudi Arabian

Compliance (ICCP) Yes **SABS** Yes

¹Configurations of the HP Zbook Firefly 16" G9 Mobile Workstation PC that are ENERGY STAR® qualified are identified as HP Zbook Firefly 16" G9 Mobile Workstation PC ENERGY STAR on HP websites and on http://www.energystar.gov.

² Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

Technical Specifications – Displays

DISPLAYS

16.0 in WUXGA (1920 x 1200) Anti-Glare UWVA LED NTSC NB2X 250 eDP 1.2 w/o PSR 45 bent LCD Panel

 Outline Dimensions (W x H)
 350.380 x 226.170 (max)

 Active Area
 344.678 x 215.424 (typ)

Weight 390 (max)

Diagonal Size 16

Thickness 3.0 / 5.0 (max)
Interface eDP 1.2
Surface Treatment Anti-Glare

Touch enabled No

Contrast Ratio1000:1(typ)Refresh Rate60 HzBrightness250 nits

Pixel Resolution Pitch 1920 x 1200 (WUXGA)

Format RGB Stripe

Backlight WLED **Color Gamut Coverage** NTSC 45%

Color Depth 6

Viewing Angle UWVA 89/89/89

Low Blue Light No

Power Consumption (W,

EBL@ 150nits max/ 200nits 2.70 (max) / 2.40 (max)

max)

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

16.0 in WUXGA (1920 x 1200) Anti-Glare UWVA LED NTSC NB2X 250 TOP eDP 1.2 w/o PSR 45 bent LCD Panel

 Outline Dimensions (W x H)
 350.680 x 226.470 (max)

 Active Area
 344.680 x 215.420 (typ)

Weight 400 (max)

Diagonal Size 16

Thickness 3.0 / 5.0 (max)
Interface eDP 1.2
Surface Treatment Anti-Glare
Touch enabled Yes

Contrast Ratio 1000:1(typ)
Refresh Rate 60 Hz
Brightness 250 nits

Pixel Resolution Pitch 1920 x 1200 (WUXGA)

Format RGB

BacklightWLEDColor Gamut CoverageNTSC 45%Color Depth8 bits

Viewing Angle UWVA 89/89/89

Low Blue Light No



Technical Specifications – Displays

Power Consumption (W, 2.70 (max) / 2.40 (max) EBL@ 150nits max/ 200nits max)

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications – Displays

16.0 in WUXGA (1920 x 1200) Anti-Glare UWVA WLED+LBL sRGB NB2X 400 eDP 1.4+PSR2 Low-Power 100 bent LCD Panel

 Outline Dimensions (W x H)
 350.680 x 226.470 (max)

 Active Area
 344.678 x 215.424 (typ)

Weight 330 (max)

Diagonal Size 16

Thickness 2.6 / 4.6 (max)

Interface eDP 1.4
Surface Treatment Anti-Glare

Touch enabled No

Contrast Ratio1000:1(typ)Refresh Rate60 HzBrightness400 nits

Pixel Resolution Pitch 1920 x 1200 (WUXGA)

Format RGB

BacklightWLEDColor Gamut CoveragesRGB 100%Color Depth8 bits

Viewing Angle UWVA 89/89/89

Low Blue Light Yes

Power Consumption (W, 1.60 (max) / 1.95 (max)

EBL@ 150nits max/ 200nits

max)

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

16.0 in WUXGA (1920 x 1200) Anti-Glare UWVA WLED+LBL sRGB NB2Y 1000 eDP 1.3+PSR 100 PrivacyG4 Plus bent LCD Panel

 Outline Dimensions (W x H)
 349.980 x 225.420 (max)

 Active Area
 344.680 x 215.420 (typ)

Weight 310 (max)

Diagonal Size 16

Thickness 2.2 / 3.9 (max)
Interface eDP 1.3

Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio 1500:1 (typ)
Refresh Rate 60 Hz

Brightness 1000 nits

Pixel Resolution Pitch 1920 x 1200 (WUXGA)

Format RGB

BacklightWLEDColor Gamut CoveragesRGB 100%Color Depth8 bits

Viewing Angle UWVA 85/85/85



Technical Specifications – Displays

Low Blue Light Yes

Power Consumption (W, N/A
EBL@ 150nits max/ 200nits
max)

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



Technical Specifications – Storage

STORAGE AND DRIVES

SSD 256GB 2280 PCIe-4x4 Form Factor M.2 2280 NVMe Three Layer Cell Capacity 256GB NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen4X4

Performance Maximum Sequential Read Maximum Sequential Write

4000 MB/s ±20% 2000 MB/s ±20%

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

SSD 512GB 2280 PCIe-4x4 NVMe Three Layer Cell Form Factor M.2 2280
Capacity 512GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen4X4

Performance Maximum Sequential Read Maximum Sequential Write

6400 MB/s ±20% 3500 MB/s ±20%

Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

SSD 1TB 2280 PCIe-4x4 NVMe Three Layer Cell Form Factor M.2 2280
Capacity 1TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen4X4

Performance Maximum Sequential Read Maximum Sequential Write

6400 MB/s ±20% 5000 MB/s ±20%

Logical Blocks 2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2

Technical Specifications – Storage

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

SSD 2TB 2280 PCIe-4x4 NVMe Three Layer Cell Form Factor M.2 2280
Capacity 2TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen4X4

Performance Maximum Sequential Read Maximum Sequential Write

6400 MB/s ±20% 5000 MB/s ±20%

Logical Blocks 4,000,797,360

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

256GB PCIe-4x4 2280 NVME Self Encrypted OPAL2 Three Layer Cell Solid State Drive Form Factor M.2 2280
Capacity 256GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen4X4

Performance Maximum Sequential Read Maximum Sequential Write

4000 MB/s ±20% 2000 MB/s ±20%

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TCG Opal 2.0; TRIM; L1.2

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

512GB PCIe-4x4 2280 NVME Self Encrypted OPAL2 Three Layer Cell Solid State Drive Form Factor M.2 2280
Capacity 512GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen4X4

Performance Maximum Sequential Read Maximum Sequential Write

6400 MB/s ±20% 3500 MB/s ±20%

Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TCG Opal 2.0; TRIM; L1.2

Technical Specifications – Storage

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

SSD 256GB 2280 PCIe NVMe Value Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

1500 MB/s ±20% 750 MB/s ±20%

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

SSD 512GB 2280 PCIe NVMe Value

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

Performance Maximum Sequential Read Maximum Sequential Write

1500 MB/s ±20% 750 MB/s ±20%

Logical Blocks 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features Pyrite 2.0; TRIM; L1.2

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel AX211 Wi-Fi 6E +BT Wireless LAN Standards IEEE 802.11a 5.2 M.2 160MHz CNVi IEEE 802.11b World-Wide WLAN vPro IEEE 802.11q IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v Interoperability Wi-Fi certified **Frequency Band** 802.11b/g/n/ax • 2.402 - 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 - 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 - 5.850 GHz • 5.955 - 6.415 GHz • 6.435 - 6.515 GHz • 6.535 - 6.875 GHz • 6.895 - 7.115 GHz **Data Rates** • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: max 300Mbps • 802.11ac: 1733Mbps 802.11ax : max 2.4Gbps **Direct Sequence Spread Spectrum Modulation** OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM Security¹ • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

AES-CCMP: 128 bit in hardware

• 802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

 WPA2 certification WPA3 certification • IEEE 802.11i

WAPI

Network Architecture Ad-hoc (Peer to Peer)

Models

Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points



Technical Specifications – Networking

• 802.11b: +17dBm minimum • 802.11g: +16dBm minimum • 802.11a: +17dBm minimum

802.11n HT20(2.4GHz): +14dBm minimum
802.11n HT40(2.4GHz): +13dBm minimum
802.11n HT20(5GHz): +14dBm minimum
802.11n HT40(5GHz): +13dBm minimum
802.11ac VHT80(5GHz): +10dBm minimum
802.11ac VHT160(5GHz): +10dBm minimum
802.11ax HE40(2.4GHz): +12dBm minimum
802.11ax HE80(5GHz): +10dBm minimum

802.11ax HE160(5GHz): +10dBm minimum

Power Consumption • Transmit mode 2.0 W

Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode 50 mW (WLAN unassociated)

Connected Standby 10mW

Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ •802.11b, 1Mbps: -93.5dBm maximum

•802.11b, 11Mbps: -84dBm maximum • 802.11a/g, 6Mbps: -86dBm maximum • 802.11a/g, 54Mbps: -72dBm maximum • 802.11n, MCS07: -67dBm maximum • 802.11n, MCS15: -64dBm maximum

802.11ac, MCS0(VHT80): -84dBm maximum
802.11ac, MCS9(VHT80): -59dBm maximum
802.11ac, MCS9(VHT160): -58.5dBm maximum
802.11ax, MCS11(HE40): -57dBm maximum
802.11ax, MCS11(HE80): -54dBm maximum
802.11ax, MCS11(HE160): -53.5dBm maximum

Antenna Type High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard

Dimensions 1. Type 2230 : 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230 : 2.8g

2. Type 1216: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)
Operating 10% to 90% (non-condensing)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating Non- 0 to 10,000 ft (3,048 m)

operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio Off; LED Off – Radio ON

Technical Specifications – Networking

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1/5.2 Wireless Technology

Frequency Band 2402 to 2480 MHz

Number of Available Channels Legacy: 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

Data Rates and Throughput Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of + 9.5 dBm for BR and

EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW Selective Suspend: 17 mW

Bluetooth Software Supported

Link Topology

Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management ETS 300 328, ETS 300 826 **Certifications** Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles Supported BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

BT5.2

ESR9/10 Compliance

LE Advertisement Extensions Channel Selection Algo

Limited High Duty Cycle Non-Connectable Advertising

2Mbps LE LE Long Range

Security & Manageability

Intel® vPro® support with appropriate Intel® chipset components

* Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, and Windows 11 to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.



Technical Specifications – Networking

Intel AX211 Wi-Fi 6E +BT Wireless LAN Standards IEEE 802.11a IEEE 802.11b 5.2 M.2 160MHz CNVi World-Wide WLAN non-IEEE 802.11g **vPro** IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v Interoperability Wi-Fi certified **Frequency Band** 802.11b/g/n/ax • 2.402 - 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 - 5.25 GHz • 5.25 - 5.35 GHz • 5.47 - 5.725 GHz • 5.825 – 5.850 GHz • 5.955 - 6.415 GHz • 6.435 - 6.515 GHz • 6.535 - 6.875 GHz • 6.895 – 7.115 GHz **Data Rates** • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: max 300Mbps 802.11ac: 1733Mbps • 802.11ax: max 2.4Gbps Modulation Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM , 1024QAM Security¹ • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification WPA3 certification • IEEE 802.11i WAPI **Network Architecture** Ad-hoc (Peer to Peer) Models Infrastructure (Access Point Required) Roaming IEEE 802.11 compliant roaming between access points



802.11b: +17dBm minimum802.11g: +16dBm minimum

Output Power²

Technical Specifications – Networking

• 802.11a: +17dBm minimum

802.11n HT20(2.4GHz): +14dBm minimum
802.11n HT40(2.4GHz): +13dBm minimum
802.11n HT20(5GHz): +14dBm minimum
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802.11ac VHT160(5GHz): +10dBm minimum
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• Receive mode 1.6 W

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 Idle mode 50 mW (WLAN unassociated)

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802.11 compliant power saving mode

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802.11ac, MCS0(VHT80): -84dBm maximum
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LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

BT5.2

ESR9/10 Compliance

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Limited High Duty Cycle Non-Connectable Advertising

2Mbps LE LE Long Range

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Technical Specifications – Networking

Intel® 5G Solution 5000

Technology/Operating bands

WCDMA/HSPA+ operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) LTE FDD/TDD operating bands: Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) Band 3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL) Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL) Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL) Band 14: 788 to 798 MHz (UL), 758 to 768 MHz (DL) Band 17: 704 to 716 MHz (UL), 734 to 746 MHz (DL) Band 18: 815 to 830 MHz (UL), 860 to 875 MHz (DL) Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL) Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) Band 25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL) Band 26: 814 to 849 MHz (UL), 859 to 894 MHz (DL) Band 28: 703 to 748 MHz (UL), 758 to 803 MHz (DL) Band 29: 717 to 728 MHz (DL) Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL) Band 32: 1452 to 1496 MHz (DL) Band 34: 2010 to 2025 MHz (UL/DL) Band 38: 2570 to 2620 MHz (UL/DL) Band 39: 1880 to 1920 MHz (UL/DL) Band 40: 2300 to 2400 MHz (UL/DL) Band 41: 2496 to 2690 MHz (UL/DL) Band 42: 3400 to 3600 MHZ (UL/DL) Band 43: 3400 to 3800 MHZ (UL/DL) Band 46: 5150 to 5925 MHZ (DL) Band 48: 3550 to 3700 MHZ (UL/DL) Band 66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) n1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL) n2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL) n3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL) n5: 824 to 849 MHz (UL), 869 to 894 MHz (DL) n7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL) n8: 880 to 915 MHz (UL), 925 to 960 MHz (DL) n20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) n25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL) n28: 703 to 748 MHz (UL), 758 to 803 MHz (DL) n38: 2570 to 2620 MHz (UL/DL) n40: 2300 to 2400 MHz (UL/DL) n41: 2496 to 2690 MHz (UL/DL) n48: 3550 to 3700 MHZ (UL/DL) n66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL)



n77: 3300 to 4200 MHz (UL/DL)

Technical Specifications – Networking

n78: 3300 to 3800 MHz (UL/DL) n79: 4400 to 5000 MHz (UL/DL)

Wireless protocol standards

5GNR Air Interface 3GPP Rel15 5G NR sub-6

LTE Rel14

20 layers and 2 Gbps downlink (DL) throughput – 4 × 4 MIMO across 5x CA

200 Mbps/uplink (UL) throughput - 40 MHz ULCA and 256 QAM

WCDMA R99,

3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands GPS: L1 (1575.42MHz)

GLONASS: L1 (1602MHz) BeidouB1(1561.098MHz) Galileo E1 (1575.42) QZSS(1575.42 MHz)

Maximum data rates

SA 5G/NR sub-6 Peak: DL4.67Gbps/ UL 1.25Gbps 5G NSA sub 6G : DL: 3.8 Gbps/UL 700Mbps

LTE: ue-CategoryDL 19, (DL: 1.6 Gbps) ue-CategoryUL 13, (UL: 150Mbps)

DC-HSPA+: 42 Mbps (Download), 11.5 Mbps (Upload)

Maximum output power

LTE: 23 dBm in all band except B41

LTE B41 HPUE = 26dBm

NR: 23 dBm in all band except n41, n77, n78 and n79

LTE n41, n77, n78 and n79 HPUE = 26dBm

HSPA+: 23.5 dBm 5G Sub 6 : 2500 mA

Maximum power consumption

LTE : 1,300 mA (peak) ; 1100 mA (average)

HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 8 q

Dimensions 52 mm × 30 mm × 2.6 mm

(Length x Width x Thickness)

* Intel 5G module is optional and must be configured at the factory. Module designed for 5G NR NSA (non-standalone) networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP. Module requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Data connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select platforms and select countries, where carrier supported.

Intel® XMM™ 7560 R+ LTE-Advanced Pro

Technology/Operating bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 14 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30),

1700/2100 (Band 66), 600 (band 71).

TDD LTE: 2100 (Band 34), 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41), 3500

(Band 42), 3700 (Band 43), 3700 (band 48), 5200 (Band 46 RX only) MHz;

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz



Technical Specifications – Networking

Wireless protocol 3GPP Release 12 LTE Specification DL-CAT.16, DL 100MHz BW throughput up to 978Mbps; UL-CAT.13

standards 40MHz throughput up to 150Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone GPS/Beidou/Glonass, A-GPS (MS-A, MS-B)

GPS Bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz

Maximum Data Rates LTE: 978 Mbps (Download), 150 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum Output Power LTE: 23 dBm in all band except B41

LTE B41 HPUE = 26dBm HSPA+: 23.5 dBm

Maximum Power LTE: 1,200 mA (peak); 900 mA (average)
Consumption HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 g

Dimensions 42 x 30 x 2.3 mm

(Length x Width x Thickness)

*4G LTE module is optional, must be configured at the factory, requires activation and separately purchased service contract.

Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

Near Field Communications Controller (optional)

Dimensions (L x W

x H) Module 25 mm by 10 mm by 2.0 mm

Chipset NPC100 System interface I2C

NFC RF standards ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

NFC Forum Support Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD)

Mode(1) ISO/IEC 14443 B

ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

ISO/IEC 14443 A

FeliCa

Jewel and Topaz cards

Card Emulation (PICC- ISO/IEC 14443 A

VICC) Mode(1) ISO/IEC 14443 B and B'

MIFARE FeliCa

Frequency 13.56 MHz

NFC Modes Supported Reader/Writer, Peer-to-Peer **Raw RF Data Rates** 106, 212, 424, 848 kbps



Technical Specifications - Networking

Operating

temperature 0°C to 70°C

Storage temperature -20°C to 125°C

Humidity 10-90% operating 5-95% non-operating

Supply Operating

voltage 4.35 to 5.25 Volts **I/O Voltage** 1.8V or 3.3V

Power Consumption Booster enable, VBAT= 3.3V,

VCC_BOOST = 5V) Polling
Mode Power Detected
Consumption, Tag Type

Typical

Detected Test Total 283.8 mA
Tag Type 1 Net Module 236.8 mA
Detected Test Total 288.8 mA

7.3 mA

Tag Type 2Net Module 241.8 mADetected TestTotal 287.7 mATag Type 3Net Module 240.7 mADetected TestTotal 282.3 mA

Tag Type 4 Total 282.3 mA Net Module 235.3 mA

Antenna Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is

external to module.

AUDIO

HD Stereo Codec Realtek ALC3315

Audio I/O Ports Headset: CTIA only and Headphone-out

Internal Speaker

Amplifier Cirrus Logic High-Efficiency Boosted Class D Amplifier

Multi-streaming Capable Playback multi-streaming can be enabled in the audio control panel to allow independent audio.

Following MSFT Behaviour

Sampling DAC: 44.1k/48kHz

ADC: 48kHz

Wavetable Syntheses

Analog Audio Support 3.5mm Headset: CTIA only and Headphone-out

of Channels on Line-

Out

Internal Speaker Yes

FINGERPRINT READER

Sensor vendor Synaptics FS7604

Sensor type Capacitive DPI resolution 363DPI

Scan area 7.4x6mm sensor area

False Rejection Rate <1%
False Acceptance Rate 1:50K FAR

Mobile Voltage Operation Mobile Voltage Operation: 3.0V to 3.6V

Operating Temperature Operating Temperature: 0~60°C



Technical Specifications - Networking

Current Consumption

Image

Current Consumption Image: 100mA Max

Low Latency Wait For

Finger

Low Latency Wait For Finger: 260 uA

Capture Rate Capture Rate: <30msec per image

ESD Resistance ESD Resistance: IEC 61000-4-2 4B (+/-15KV) **Detection Matrix** Detection Matrix: 363 dpi / 7.4x6mm sensor area

POWER

AC Adapter 65 Watt nPFC Dimensions Slim USB type C Straight Weight

1.8m

 Dimensions
 88x53.5x21mm

 Weight
 unit: 220g +/- 10g

Input Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A

86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range 47 ~ 63 Hz

Input AC current 1.6 A at 90 VAC and maximum load

Output Output power 65W

DC output 5V/9V/12V/15V/20V **Hold-up time** 5ms at 115 Vac input

Output current limit <8.0A

Connector C6

Environmental Design Operating 32° to 95° F (0° to 35° C)

temperature

Non-operating (storage) -4° to 185° F (-20° to 85° C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety Certifications

Eg:

*CE Mark – full compliance with LVD and EMC directives

* Worldwide safety standards – IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV; Agency approvals – C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class

B, CISPR32 Class B, CCC, NOM-001 NYCE.

* MTBF – over 200,000 hours at 25°C ambient condition.



Technical Specifications – Power

AC Adapter 65 Watt nPFC Dimensions Standard USB type C Straight 1.8m

Weight Input

Output

90.0mm*51.0mm*28.5mm

250g +/-10%

Input Efficiency

Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec:

5V:81.5% 9V:86.7% 12V:88% 15V:88% 20V:89%

Input frequency range 47 ~ 63 Hz

Input AC current

Max. 1.6 A at 90 Vac

Output power

5V/15W 9V/27W 12V/60W 15V/60W

20V/65W 5V/9V/12V/15V/20V **DC** output Hold-up time 5ms at 115 Vac input

Output current limit <8.0A

Connector C6

Environmental Design

Operating temperature

32° to 95° F (0° to 35° C)

Non-operating (storage)

temperature

-4° to 185° F (-20° to 85° C)

0 to 16,400 ft (0 to 5000m) **Altitude**

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications

*CE Mark – full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV; Agency approvals – C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class

B, CISPR32 Class B, CCC, NOM-001 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

HP 100W+10W Slim USB- Dimensions C+USB-A Straight AC **Power Adapter Kenting**

Weight Input

136x60x22mm unit: 365g +/- 10g

Input Efficiency Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec:

5VusbA: 73.62% 5VusbC: 81.5% 9V:86.7% 12V:88% 15V:89% 20V:89%

> 90% efficiency at 100W (20V/5A) output

condition

Input frequency range 47 ~ 63 Hz

Input AC current 1.6 A at 90 VAC and maximum load

Technical Specifications – Power

Output **Output power** 110W

> **DC** output 5VusbA/5V/9V/12V/15V/20V

Hold-up time 5ms at 115 Vac input

Output current limit <6.25A

Connector

USB Type C

Operating **Environmental Design**

32° to 95° F (0° to 35° C) temperature

Non-operating (storage)

temperature

-4° to 185° F (-20° to 85° C)

Altitude 0 to 16.400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety

*CE Mark – full compliance with LVD and EMC directives Certifications

> * Worldwide safety standards - IEC60950-1 and/or IEC62368-1, EN60950-1 and/or EN62368-1, UL60950-1 and/or UL62368-1, Class1, SELV; Agency approvals – C-UL-US, NORDICS, DENAN, EN55032 Class B, FCC Class

B, CISPR32 Class B, CCC, NOM-001 NYCE.

* MTBF – over 200.000 hours at 25°C ambient condition.

HP 3-cell Long Life Li-Ion Dimensions (H x W x L)

(51 WHr)

251.8*70.3*6.82mm (9.91*2.77*0.27 inch)

Weight 0.229kg +/- 10g(0.505 lb)

Cells/Type 3cell Lithium-Ion Polymer cell / 566075 11.58V Energy Voltage Amp-hour capacity 4.431Ah

Watt-hour capacity 51.3Wh

Temperature Operating (Charging) 32° to 113° F (0° to 45° C)

> 14° to 140° F (-10° to 60° C) Operating (Discharging)

Fuel Gauge LED NA

Warranty Follow product spec

Optional Travel Battery No

Available

*Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.

HP 6-cell Long Life Li-Ion Dimensions (H x W x L) 303.2*90.1*6.82mm(11.94*3.55*0.27 inch) (76WHr)

Weight 0.357kg +/- 10g(0.787 lb)

Cells/Type 6cell Lithium-Ion Polymer cell / 564975 11.58V Energy Voltage 6.565Ah

Amp-hour capacity Watt-hour capacity 76Wh

Temperature Operating (Charging) 32° to 113° F (0° to 45° C)

Operating (Discharging) 14° to 140° F (-10° to 60° C)

Fuel Gauge LED NA

Technical Specifications – Power

Warranty Follow product spec

Optional Travel Battery N

Available

*Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.



Technical Specifications - Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- US Federal Energy Management Program (FEMP)
- EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO Certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*

Sustainable Impact Specifications

- Ocean-bound plastic in Speaker Box¹
- 35% post-consumer recycled plastic²
- External Power Supply 90% Efficiency
- Low halogen3
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable⁴
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable⁵
- Bulk packaging available

11EVAC COU-

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

220VAC EUH-

Energy Consumption (in accordance with US ENERGY STAR® test method)

31 MK LEST IIIETIIOU)	I ISVAC, OUNZ	ZOVAC, JUNZ	TOUVAC, SUNZ
Normal Operation (Short idle)	5.71 W	6.14 W	5.89 W
Normal Operation (Long idle)	1.14 W	1.28 W	1.23 W
Sleep	1.14 W	1.28 W	1.23 W
Off	0.42 W	0.44 W	0.42 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	19.5 BTU/hr	21 BTU/hr	20.1 BTU/hr
Normal Operation (Long idle)	3.9 BTU/hr	4.4 BTU/hr	4.2 BTU/hr
Sleep	3.9 BTU/hr	4.4 BTU/hr	4.2 BTU/hr
Off	1.4 BTU/hr	1.5 BTU/hr	1.4 BTU/hr

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.



100VAC EOU-

Technical Specifications – Environmental

Declared Noise Emissions	Sound Power	Sound Pressure
(in accordance with	(L _{wad} , bels)	(L _{pAm} , decibels)
ISO 7779 and ISO 9296)		
Typically Configured – Idle	2.3	16.1
Fixed Disk – Random writes	2.5	17.8
Optical Drive – Sequential reads	3.2	22.9

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive – 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 3.5% recycle-able when properly disposed of at end of life.

Packaging Materials	External:	PAPER/Corrugated	287 g
		PAPER/Paperboard	72 g
		PAPER/Paper	4 g
		PAPER/Molded Pulp	162 g
	Internal:	PLASTIC/Polyethylene low density – LDPE	13 g

The plastic packaging material contains at least 100% recycled content.

The corrugated paper packaging materials contains at least 35.6% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Technical Specifications - Environmental

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers.



Technical Specifications – Environmental

These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Footnotes

¹Percentage of ocean-bound plastic contained in each component varies by product

²Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.

³External power supplies, WWAN modules, power cords, cables and peripherals excluded.

⁴100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.

⁵Fiber cushions made from 100% recycled wood fiber and organic materials.



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part #
Audio/Video	HP Wired USB-A Stereo Headset	428K6AA
	HP Wired 3.5mm Stereo Headset	428K7AA
Cases	HP Executive 15.6 Backpack	6KD07AA
	HP Executive 15.6 Top Load	6KD06AA
	HP Prelude G2 15.6 Backpack	1E7D6AA
	HP Prelude G2 15.6 Top Load	1E7D7AA
	HP Prelude Pro Recycled 15.6Backpack	1X644AA
	HP Prelude Pro Recycled 15.6 Top Load	1X645AA
	HP Renew Business 17.3 Laptop Backpack	3E2U5AA
	HP Renew Business 17.3 Laptop Bag	3E2U6AA
	HP Renew Business 15.6 Laptop Bag	3E5F8AA
Docking station	HP 120W G2 Dock	2UK37AA
	HP 120W G2 Dock w/Audio	3YE87AA
	HP 230W G2 Dock w/Combo Cable	3TR87AA
	HP USB-C 120W G5 Dock	5TW10AA
	HP USB-C/A 120W G2 Universal Dock	5TW13AA
	HP Thunderbolt Dock Audio Module	3AQ21AA
	HP USB-C Dock G5	26D32AA
	HP 120W Thunderbolt Dock	6HP48AA
	HP TB Dock 120W G2 Cable	3XB94AA
	HP TB Dock 230W G2 Cable	3XB95AA
	HP TB Dock G2 Combo Cable	3XB96AA
	HP Thunderbolt 120W G4 Dock	4J0A2AA
	HP Thunderbolt 280W G4 Dock w/Combo Cable	4J0G4AA
Hub	HP USB-C Travel Dock G2	7PJ38AA
	HP USB-C to USB-A Hub	Z6A00AA
Adapter	HP USB-C to RJ45 Adapter G2	4Z527AA
	HP USB 3.0 to Gigabit RJ45 Adapter G2	4Z7Z7AA
	HP HDMI to DVI Adapter	F5A28AA
	HP HDMI to VGA Adapter	H4F02AA
	HP USB to Gigabit RJ45 Adapter	N7P47AA
	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to HDMI 2.0 Adapter	1WC36AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to VGA Adapter	N9K76AA
Keyboard/Combo	HP 975 USB+BT Dual-Mode Wireless Keyboard	3Z726AA
	HP 455 Programmable Wireless Keyboard	4R177AA
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Options and Accessories (sold separately and availability may vary by country)

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	HP 125 WD USB Keyboard	266C9AA
	HP 320K WD USB Keyboard	9SR37AA
	HP 655 Wireless Keyboard and Mouse Combo	4R009AA
	HP 225 Wired Mouse and Keyboard Combo	286J4AA
	HP 235 Wireless Mouse and Keyboard Combo	1Y4D0AA
	HP Slim Wireless Keyboard and Mouse	T6L04AA
	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA
	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA
Memory	HP 8GB DDR5 4800 SODIMM Memory	5S4C3AA
	HP 16GB DDR5 4800 SODIMM Memory	5S4C4AA
	HP 32GB DDR5 4800 SODIMM Memory	5S4COAA
Mouse	HP USB Premium Wireless Mouse	1JR31AA
	HP 435 Multi-Device Wireless Mouse	3B4Q5AA
	HP 125 USB-A Wired Mouse	265A9AA
	HP 128 USB Laser Wired Mouse	265D9AA
	HP 320M USB-A Wired Mouse	9VA80AA
	HP Creator USB-A+Bluetooth 935 Wireless Mouse Black	1D0K8AA
	HP USB-A+Bluetooth Multi-Device 635 Wireless Mouse Black	1D0K2AA
	HP USB-A+Bluetooth Travel Bluetooth Mouse	6SP30AA
Power	HP 65W USB-C Auto AC Power Adapter	5TQ76AA
	HP 45W USB-C G2 AC Power Adapter	1HE07AA
	HP 45W USB-C LC AC Power Adapter	1MZ01AA
	HP 65W USB-C LC AC Power Adapter	1P3K6AA
	HP 65W Gallium Nitride USB-C Laptop Charger	600Q7AA
	HP 65W Gallium Nitride USB-C Laptop Charger	600Q8AA
Commodity	HP USB DVD-Writer EXT ODD	F2B56AA
	HP Nano Keyed Cable Lock	1AJ39AA
	HP Nano Master Keyed Cable Lock	1AJ40AA
	HP SureKey Standard/Nano/Wedge Cable Lock	6UW42AA
	HP 16GB (1x16GB) DDR4 3200 1.2v SODIMM Memory	286J1AA
	HP 8GB (1x8GB) DDR4 3200 1.2v SODIMM Memory	286H8AA



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Date of change:	Version History:		Description of change:
May 20, 2022	From v1 to v2	Changed	POWER section
May 31, 2022	From v2 to v3	Changed	DRIVE CONTROLLERS section
June 29, 2022	From v3 to v4	Changed	SOFTWARE AND SECURITY section
August 10, 2022	From v4 to v5	Changed	Options and Accessories section
September 2, 2022	From v5 to v6	Changed	POWER section
September 12, 2022	From v6 to v7	Changed	At A Glance section
September 15, 2022	From v7 to v8	Removed	Tile App for Software

